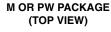
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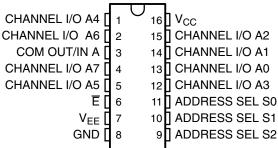
- Qualified for Automotive Applications
- Wide Analog Input Voltage Range of ±5 V Max
- Low ON Resistance
  - 70  $\Omega$  Typical (V<sub>CC</sub> V<sub>EE</sub> = 4.5 V)
  - 40  $\Omega$  Typical (V<sub>CC</sub> V<sub>EE</sub> = 9 V)
- Low Crosstalk Between Switches
- Fast Switching and Propagation Speeds
- Break-Before-Make Switching

## description/ordering information

This device is a digitally controlled analog switch that utilizes silicon-gate CMOS technology to achieve operating speeds similar to LSTTL, with the low power consumption of standard CMOS integrated circuits.

- Operation Control Voltage = 2 V to 6 V
- Switch Voltage = 0 V to 10 V
- High Noise Immunity N<sub>IL</sub> = 30%, N<sub>IH</sub> = 30% of V<sub>CC</sub>, V<sub>CC</sub> = 5 V





This analog multiplexer/demultiplexer controls analog voltages that may vary across the voltage supply range (i.e.,  $V_{CC}$  to  $V_{EE}$ ). These bidirectional switches allow any analog input to be used as an output and vice versa. The switches have low ON resistance and low OFF leakages. In addition, the device has an enable control ( $\overline{E}$ ) that, when high, disables all switches to their OFF state.

#### ORDERING INFORMATION<sup>†</sup>

T <sub>A</sub>	PACK	AGE‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC - M	Tape and reel	CD74HC4051QM96Q1	HC4051Q
-40 C to 125 C	TSSOP - PW	Tape and reel	CD74HC4051QPWRQ1	HJ4051Q

<sup>&</sup>lt;sup>†</sup> For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



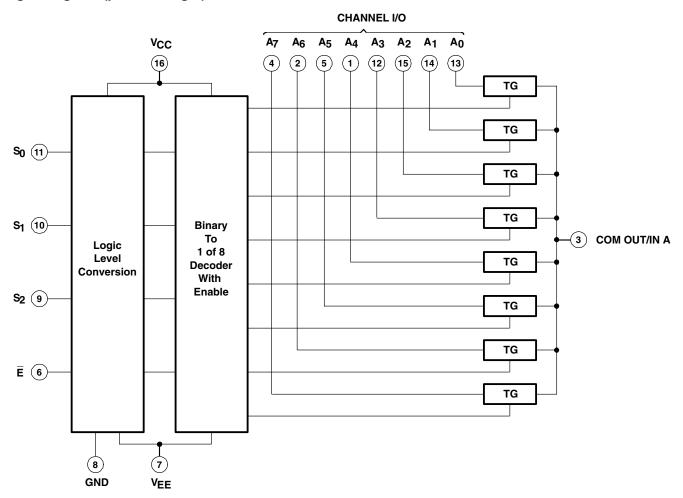
<sup>&</sup>lt;sup>‡</sup> Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

#### **FUNCTION TABLE**

	INPU	rs		ON
Ē	S <sub>2</sub>	S <sub>1</sub>	S <sub>0</sub>	CHANNEL(S)
L	L	L	L	A0
L	L	L	Н	A1
L	L	Н	L	A2
L	L	Н	Н	A3
L	Н	L	L	A4
L	Н	L	Н	A5
L	Н	Н	L	A6
L	Н	Н	Н	A7
Н	Χ	Х	Χ	None

X = Don't care

# logic diagram (positive logic)





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# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub> – V <sub>EE</sub> (see Note 1)	–0.5 V to 10.5 V
Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Supply voltage range, V <sub>EE</sub>	+0.5 V to -7 V
Input clamp current, $I_{IK}$ ( $V_I < -0.5 \text{ V or } V_I > V_{CC} + 0.5 \text{ V}$ )	±20 mA
Output clamp current, $I_{OK}$ ( $V_O < V_{EE} - 0.5 \text{ V or } V_O > V_{CC} + 0.5 \text{ V}$ )	±20 mA
Switch current ( $V_I > V_{EE} - 0.5 \text{ V or } V_I < V_{CC} + 0.5 \text{ V}$ )	±25 mA
Continuous current through V <sub>CC</sub> or GND	±50 mA
V <sub>EE</sub> current, I <sub>EE</sub>	–20 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): M package	73°C/W
PW package	108°C/W
Maximum junction temperature, T <sub>J</sub>	150°C
Lead temperature (during soldering):	
At distance $1/16 \pm 1/32$ inch $(1,59 \pm 0,79$ mm) from case for 10 s max	300°C
Storage temperature range, T <sub>stq</sub>	–65°C to 150°C

<sup>&</sup>lt;sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages referenced to GND unless otherwise specified.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

# recommended operating conditions (see Note 3)

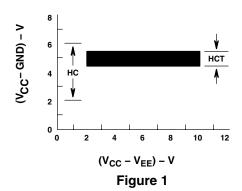
			MIN	MAX	UNIT
$V_{CC}$	Supply voltage (see Note 4)		2	6	V
	Supply voltage, V <sub>CC</sub> – V <sub>EE</sub> (see Figure 1)		2	10	V
$V_{EE}$	Supply voltage, (see Note 4 and Figure 2)		0	-6	V
	V <sub>CC</sub> :	= 2 V	1.5		
$V_{IH}$	High-level input voltage	= 4.5 V	3.15		V
	V <sub>CC</sub> :	= 6 V	4.2		
	V <sub>CC</sub> :	= 2 V		0.5	
$V_{IL}$	Low-level input voltage V <sub>CC</sub> :	= 4.5 V		1.35	V
V <sub>EE</sub> V <sub>IH</sub> V <sub>IL</sub> V <sub>I</sub> V <sub>IS</sub>	V <sub>CC</sub> :	= 6 V		1.8	
VI	Input control voltage		0	$V_{CC}$	V
$V_{IS}$	Analog switch I/O voltage		$V_{EE}$	$V_{CC}$	V
	V <sub>CC</sub> :	= 2 V	0	1000	
t <sub>t</sub>	Input transition (rise and fall) time	= 4.5 V	0	500	ns
	V <sub>CC</sub> = 6 V				
T <sub>A</sub>	Operating free-air temperature	_	-40	125	°C

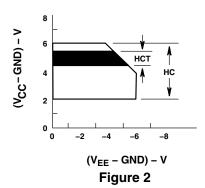
NOTES: 3. All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

4. In certain applications, the external load resistor current may include both V<sub>CC</sub> and signal-line components. To avoid drawing V<sub>CC</sub> current when switch current flows into the transmission gate inputs, the voltage drop across the bidirectional switch must not exceed 0.6 V (calculated from r<sub>on</sub> values shown in electrical characteristics table). No V<sub>CC</sub> current flows through R<sub>L</sub> if the switch current flows into the COM OUT/IN A terminal.



# recommended operating area as a function of supply voltages





# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST COI	TEST CONDITIONS			T,	<sub>4</sub> = 25°C	;	T <sub>A</sub> = -		UNIT
					MIN	TYP	MAX	MIN	MAX	
			0 V	4.5 V		70	160		240	
		$V_{IS} = V_{CC}$ or $V_{EE}$	0 V	6 V		60	140		210	
	$I_0 = 1 \text{ mA},$		-4.5 V	4.5 V		40	120		180	
r <sub>on</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> , See Figure 8		0 V	4.5 V		90	180		270	Ω
	3	$V_{IS} = V_{CC}$ to $V_{EE}$	0 V	6 V		80	160		240	
			-4.5 V	4.5 V		45	130		195	
		0 V	4.5 V		10					
$\Delta r_{\sf on}$	Between any two cha	0 V	6 V		8.5				Ω	
		-4.5 V	4.5 V		5					
	For switch OFF: When $V_{IS} = V_{CC}$ , $V_{OS}$ When $V_{IS} = V_{EE}$ , $V_{OS}$			6 V			±0.2		±2	
I <sub>IZ</sub>	For switch ON: All applicable combination voltage levels, V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	-5 V	5 V			±0.4		<u>+</u> 4	μΑ	
I <sub>IL</sub>	$V_I = V_{CC}$ or GND	0 V	6 V			±0.1		±1	μΑ	
lee	l <sub>O</sub> = 0,	When $V_{IS} = V_{EE}$ , $V_{OS} = V_{CC}$	0 V	6 V			8		160	μΑ
I <sub>CC</sub>	$V_I = V_{CC}$ or GND	When $V_{IS} = V_{CC}$ , $V_{OS} = V_{EE}$	-5 V	5 V			16		320	μА

# CD74HC4051-Q1 **ANALOG MULTIPLEXER/DEMULTIPLEXER**

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# switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 7)

PARAMETER	FROM	TO	LOAD	V <sub>EE</sub>	V <sub>CC</sub>	T <sub>A</sub> =	25°C		T <sub>A</sub> = - TO 12		UNIT			
	(INPUT)	(OUTPUT)	CAPACITANCE			MIN T	ГҮР	MAX	MIN	MAX				
			C <sub>L</sub> = 15 pF		5 V		4				ns			
					2 V			60		90				
<sup>t</sup> pd	IN	OUT	0 50 5	0 V	4.5 V			12		18				
			$C_L = 50 pF$		6 V			10		15	ns			
				-4.5 V	4.5 V			8		12				
	ADDRESS SEL or E	OUT	C <sub>L</sub> = 15 pF		5 V		19							
			C <sub>L</sub> = 50 pF		2 V			225		340				
t <sub>en</sub>					0 50 5	0 V	4.5 V			45		68	ns	
					6 V			38		57				
				-4.5 V	4.5 V			32		48				
			C <sub>L</sub> = 15 pF		5 V		19							
					2 V			225		340				
t <sub>dis</sub>	ADDRESS SEL or E	OUT	0 50 5	0 V	4.5 V			45		68	ns			
	OI E			C <sub>L</sub> = 50 pF	$C_L = 50 \text{ pF}$	C <sub>L</sub> = 50 pF		6 V			38		57	
					1		-4.5 V	4.5 V			32		48	
C <sub>I</sub>	Control		C <sub>L</sub> = 50 pF					10		10	pF			

# operating characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C, Input $t_r$ , $t_f$ = 6 ns

PARAMETER	TYP	UNIT
C <sub>pd</sub> Power dissipation capacitance (see Note 5)	50	pF

NOTE 5:  $\,C_{pd}$  is used to determine the dynamic power consumption, per package.

 $P_D = C_{pd} V_{CC}^2 f_l + \Sigma (C_L + C_S) V_{CC}^2 f_O$   $f_O = \text{output frequency}$ 

f<sub>I</sub> = input frequency

C<sub>L</sub> = output load capacitance

 $C_S$  = switch capacitance

V<sub>CC</sub> = supply voltage

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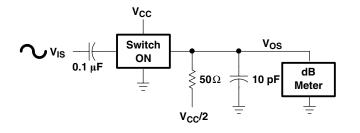
# analog channel characteristics, T<sub>A</sub> = 25°C

	PARAMETER	TEST CONDITIONS	V <sub>EE</sub>	V <sub>CC</sub>	MIN TYP	MAX	TINU
CI	Switch input capacitance				5		pF
C <sub>COM</sub>	Common output capacitance				25		pF
4	Minimum switch frequency	See Figure 3 and Figure 9, and	-2.25 V	2.25 V	145		N41.1-
<sup>T</sup> max	response at -3 dB	Notes 6 and 7	-4.5 V	4.5 V	180		MHz
	Cinaa diata dia a	Can Figure 4	-2.25 V	2.25 V	0.035		0/
	Sine-wave distortion	See Figure 4	-4.5 V	4.5 V	0.018		%
	E or ADDRESS SEL to	One Figure 5, and Nation 7 and 0	-2.25 V	2.25 V	(TBD)		
	switch feed-through noise	See Figure 5, and Notes 7 and 8	-4.5 V	4.5 V	(TBD)		mV
	Switch OFF signal feed	See Figure 6 and Figure 10, and	-2.25 V	2.25 V	-73		dB
	through	Notes 7 and 8	-4.5 V	4.5 V	-75		uБ

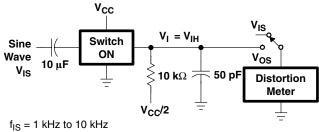
NOTES: 6. Adjust input voltage to obtain 0 dBm at  $V_{OS}$  for  $f_{IN}$  = 1 MHz. 7.  $V_{IS}$  is centered at  $(V_{CC} - V_{EE})/2$ .

- 8. Adjust input for 0 dBm.

# PARAMETER MEASUREMENT INFORMATION







**Figure 4. Sine-Wave Distortion Test Circuit** 

## PARAMETER MEASUREMENT INFORMATION

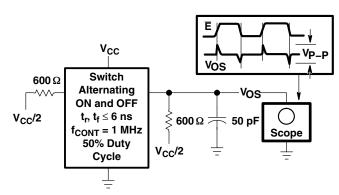


Figure 5. Control to Switch Feedthrough Noise Test Circuit

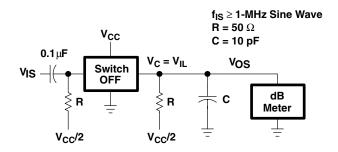
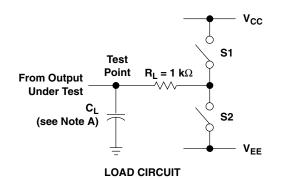
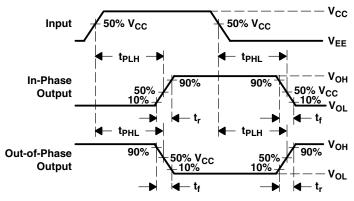


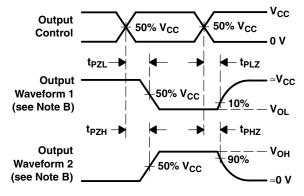
Figure 6. Switch OFF Signal Feedthrough Test Circuit

#### PARAMETER MEASUREMENT INFORMATION



PARAI	METER	S1	S2		
<b>+</b>	t <sub>PZH</sub>	Open	Closed		
t <sub>en</sub>	t <sub>PZL</sub>	Closed	Open		
t <sub>dis</sub>	t <sub>PHZ</sub>	Open	Closed		
cais	t <sub>PLZ</sub>	Closed	Open		
t <sub>pd</sub>		Open	Open		





VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

VOLTAGE WAVEFORMS
OUTPUT ENABLE AND DISABLE TIMES

NOTES: A. C<sub>L</sub> includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50~\Omega$ ,  $t_f = 6$  ns,  $t_f = 6$  ns.
- D. For clock inputs, f<sub>max</sub> is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- G.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- H. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.

Figure 7. Load Circuit and Voltage Waveforms



## **TYPICAL CHARACTERISTICS**

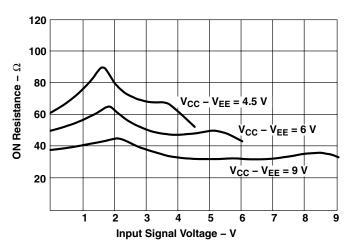


Figure 8. Typical ON Resistance vs Input Signal Voltage

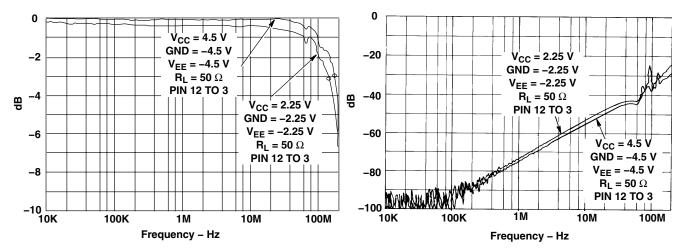


Figure 9. Channel ON Bandwidth

Figure 10. Channel OFF Feedthrough

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#### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
CD74HC4051QM96G4Q1	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC4051Q	Samples
CD74HC4051QM96Q1	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC4051Q	Samples
CD74HC4051QPWRG4Q1	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HJ4051Q	Samples
CD74HC4051QPWRQ1	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HJ4051Q	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE**: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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# **PACKAGE OPTION ADDENDUM**

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#### OTHER QUALIFIED VERSIONS OF CD74HC4051-Q1:

● Catalog: CD74HC4051

● Enhanced Product : CD74HC4051-EP

Military: CD54HC4051

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications
- Military QML certified for Military and Defense Applications

# **PACKAGE MATERIALS INFORMATION**

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# TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC4051QPWRG4Q1	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC4051QPWRQ1	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

# **PACKAGE MATERIALS INFORMATION**

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## \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC4051QPWRG4Q1	TSSOP	PW	16	2000	356.0	356.0	35.0
CD74HC4051QPWRQ1	TSSOP	PW	16	2000	367.0	367.0	35.0

# D (R-PDS0-G16)

# PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.





SMALL OUTLINE PACKAGE



#### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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